

## Sn95.5/Ag4.0/Cu0.5 Solder Spheres for BGAs

### Product Highlights

Chip Quik® BGA solder spheres are manufactured from virgin materials to meet or exceed the requirements of building or repairing BGA packages. Chip Quik® BGA solder spheres also exceed both the IPC and MIL standards for purity levels and size tolerances. Nominal sizes are available from 0.20 to 0.76 mm (8 to 30 mil).

### Product Specifications

Part Number	Alloy	Melting Point	Diameter	Quantity (by weight)
CQ-SS-SAC405-0.20MM-25000	Sn95.5/Ag4.0/Cu0.5	217°C (423°F)	0.20 mm	25,000
CQ-SS-SAC405-0.25MM-25000			0.25 mm	25,000
CQ-SS-SAC405-0.30MM-25000			0.30 mm	25,000
CQ-SS-SAC405-0.35MM-25000			0.35 mm	25,000
CQ-SS-SAC405-0.40MM-25000			0.40 mm	25,000
CQ-SS-SAC405-0.45MM-25000			0.45 mm	25,000
<b>CQ-SS-SAC405-0.50MM-25000</b>			<b>0.50 mm</b>	<b>25,000</b>
CQ-SS-SAC405-0.60MM-25000			0.60 mm	25,000
CQ-SS-SAC405-0.76MM-25000			0.76 mm	25,000

Shelf Life: >24 months

### Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

### Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): Yes  
 RoHS 3 Directive (EU) 2015/863: Yes